

09/890455

7-17-02 PD

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hiroaki INOUË et al.

Attn: **BOX PCT**

Serial No. NEW

Docket No. 2001_1094A

Filed August 1, 2001

ELECTROLESS PLATING LIQUID AND METHOD
OF FORMING INTERCONNECTION USING SUCH
AN ELECTROLESS PLATING LIQUID

[Corresponding to PCT/JP00/09099

Filed December 21, 2000]

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Prior to calculating the filing fee, please amend the above-identified application as follows:

IN THE SPECIFICATION

Page 1, immediately after the title, please insert:

This application is a 371 of PCT/JP00/09099 filed December 21, 2000.

IN THE CLAIMS

Please amend claim 5 as follows:

15. (Amended) A method of forming a copper interconnection on a semiconductor device, characterized by the steps of forming an auxiliary seed layer for reinforcing a copper seed layer in an interconnection groove defined in a surface of the semiconductor device using an electroless copper plating liquid containing dihydric copper ions, a complexing agent, and an aldehyde acid, and performing an electrolytic plating process using the seed layer including said auxiliary seed